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RoHS Reflow Profile

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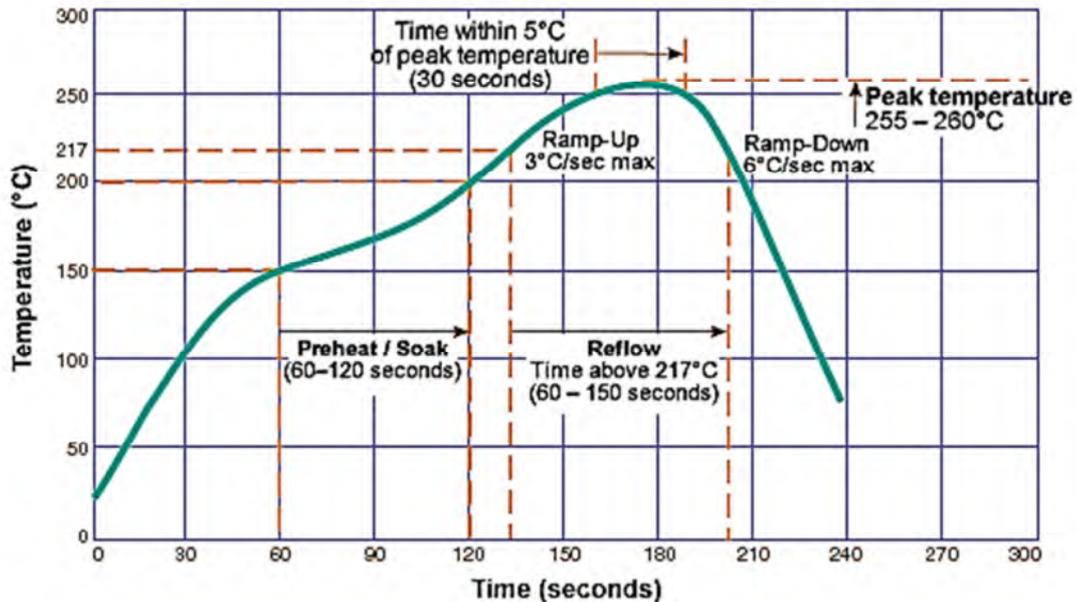
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▶ RoHS Reflow Profile

Typical RoHS Reflow Profile



Typical RoHS Reflow Profile

All Token RoHS-compliant parts are backward compatible with tin-lead soldering processes. Soldering temperature must be greater than 230°C to ensure proper melting of lead-free solder.

For all soldering methods, the optimal reflow profile for a circuit board assembly is dependent on the solder material, solder amount, flux, temperature limit of each soldered component, heat transfer characteristics of the circuit board and component materials, and the layout of all components. The temperature versus time limitation of the least robust component of the circuit board assembly ultimately may determine the actual temperature profile that must be used. For these reasons, Token does not specify soldering profiles for our components.

This typical reflow profile is based on IPC/JEDEC J-STD-020 Revision D.1 (March 2008). It is provided only as a guide.

For additional information, refer to these web sites: www.jedec.org.

Soldering surface mount components

All our RoHS-compliant parts are backward compatible with tin-lead soldering processes.
Soldering temperature must be greater than 230°C to ensure proper solder melting.

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The temperature versus time limitation of the least robust component of the circuit board assembly ultimately may determine the actual temperature profile that must be used. For these reasons, Token does not specify soldering profiles for our components.

A typical reflow profile based on IPC/JEDEC J-STD-020 Revision D.1 (March 2008) is provided only as a guide.

Soldering through-hole components

All our RoHS-compliant parts are backward compatible with tin-lead soldering processes.

For all soldering methods, the optimal soldering profile for a circuit board assembly is dependent on the solder material, solder amount, flux, temperature limit of each soldered component, heat transfer characteristics of the circuit board and component materials, and the layout of all components. The temperature vs. time limitation of the least robust component of the circuit board assembly ultimately dictates the optimal temperature profile. For this reason, Token does not provide soldering profiles for our components.

CAUTION:

All of Token's through-hole components are designed to be wave soldered and it is not recommended to use a reflow soldering procedure. The higher temperatures of reflow soldering may damage these components.

Token's through-hole components can be successfully wave soldered as long as care is taken throughout the process. For many of the components, it is essential to minimize the circuit board temperature and the time spent over the solder nozzle. In order to achieve a quality bond without damaging the components, Token recommends preheating the board for up to three minutes and limiting the time the board spends over the solder nozzle to three seconds.

